Title: METHOD FOR FILLING RECESSED MICROSTRUCTURES WITH METALLIZATION IN THE PRODUCTION OF A MICROELECTRONIC DEVICE

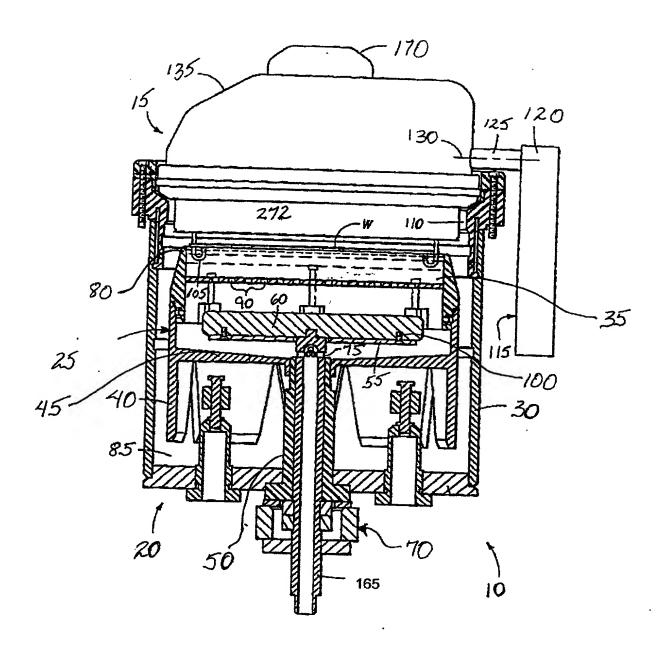
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FIG. 1



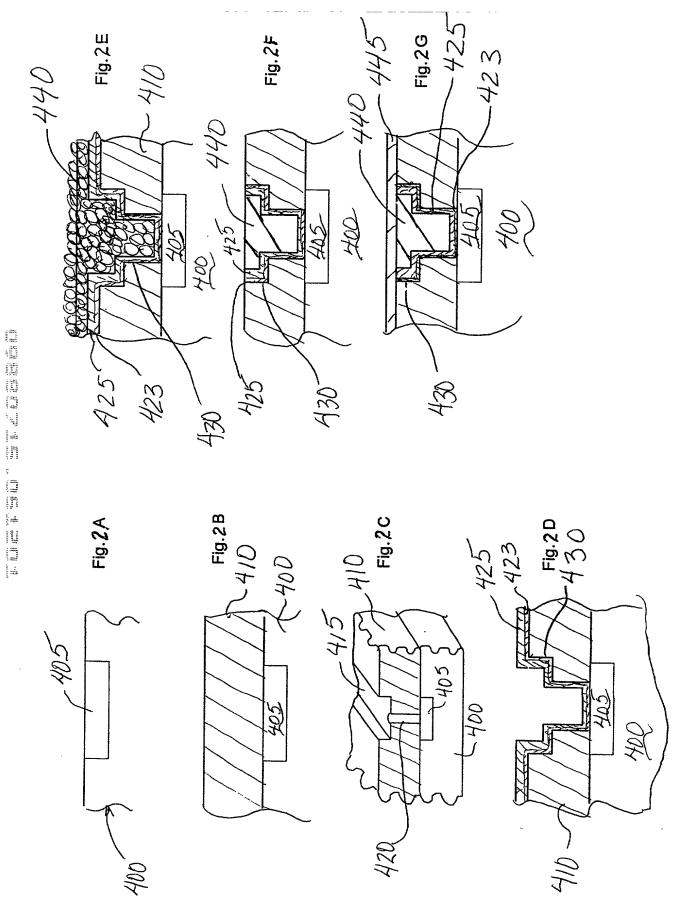
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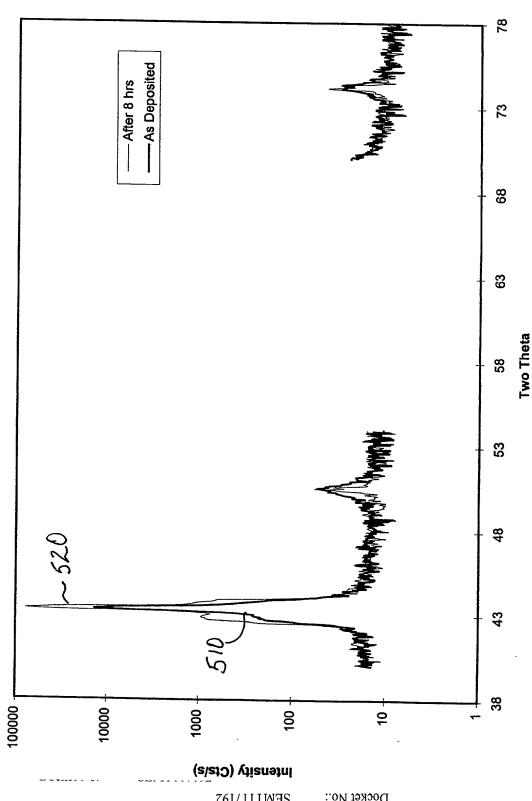
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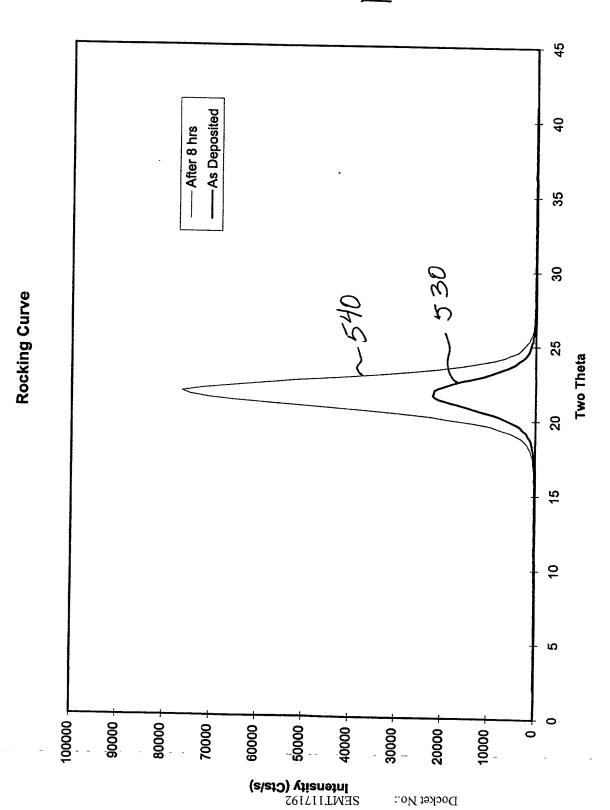
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STRUCTURES WITH METALLIZATION IN THE
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Intensity (Citsle)



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BRODUCTION OF A MICROELECTRONIC DEVICE STRUCTURES WITH METALLIZATION IN THE TILLING RECESSED MICRO-

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